

Title (en)  
SELF-ASSEMBLY OF CHIPS BY SUBSTRATE

Title (de)  
SELBSTANORDNUNG VON CHIPS MITHILFE EINES SUBSTRATS

Title (fr)  
AUTO-ASSEMBLAGE DE PUCES SUR UN SUBSTRAT

Publication  
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Application  
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Abstract (en)  
[origin: WO2009124921A1] The invention relates to a method of forming, on the surface of a substrate (2), at least one hydrophilic attachment zone (12) for the purpose of self-assembling a component or a chip (3), in which a hydrophobic zone (20), which delimits said hydrophilic attachment zone, is produced.

IPC 8 full level  
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See references of WO 2009124921A1

Citation (examination)  
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